Product Change Notification: CAAN-09WOLD265

Date:

06-Mar-2025

Product Category:

Linear Op Amps

Notification Subject:

CCB 7292 Final Notice: Qualification of palladium coated copper with gold flash (CuPdAu) as a new bond wire material for MCP603T-E/CH, MCP603T-I/CH, MCP6043T-E/CH, MCP6043T-I/CH, MCP6143T-E/CH, MCP6273T-E/CH, MCP6283T-E/CH and MCP6293T-E/CH catalog part numbers (CPN) available in 6L SOT-23 package at MTAI assembly site.

Affected CPNs:

CAAN-09WOLD265_Affected_CPN_03062025.pdf
CAAN-09WOLD265_Affected_CPN_03062025.csv

PCN Status: Final Notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.
Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change: Qualification of palladium coated copper with gold flash (CuPdAu) as a new bond wire material for MCP603T-E/CH, MCP603T-I/CH, MCP6043T-E/CH, MCP6043T-I/CH, MCP6143T-E/CH, MCP6273T-E/CH, MCP6283T-E/CH and MCP6293T-E/CH catalog part numbers (CPN) available in 6L SOT-23 package at MTAI assembly site.

Pre and Post Summary Changes:

	Pre Change	**Post Change**
Assembly Site	Microchip Technology Thailand (HQ) (MTAI)	Microchip Technology Thailand (HQ) (MTAI)

Wire Material	Au	CuPdAu
Die Attach Material	84-3J	84-3J
Molding Compound Material	G600V	G600V
Lead-Frame Material	CDA194	A194
DAP Surface Prep	Ag Spot Plated	Ag Single Ring Plated
Lead-Frame Design	See Pre and Post Change for Comparison	

*Note: C194, A194 or CDA194 Lead frame material are the same, it is just a MCHP internal labelling difference.

Impacts to Datasheet: None

Change Impact: None

Reason for Change: To improve manufacturability by qualifying palladium coated copper with gold flash (CuPdAu) as a new bond wire material.

Change Implementation Status: In Progress

Estimated First Ship Date: 25 April 2025 (date code: 2517)

Note Below EFSD: Note: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Timetable Summary:

	December 2024					**>**	**March 2025**					**April 2025**				
Work Week	49	50	51	52	53		09	10	11	12	13	14	15	16	17	18
Initial PCN Issue Date		x														
Qual Report Availability								x								

Final PCN Issue Date								x								
Estimated Implementation Date															x	

Method to Identify Change: Traceability Code

Qualification Report: Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History: December 12, 2024: Issued initial notification.
March 06, 2025: Issued final notification. Attached the Qualification Report. Provided estimated first ship date to be on April 25, 2025.

Note: The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

Attachments:

PCN_CAAN-09WOLD265_Pre and Post Change Summary.pdf
PCN_CAAN-09WOLD265_Qual_Report.pdf

Please contact your local **Microchip sales office** with questions or concerns regarding this notification.

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